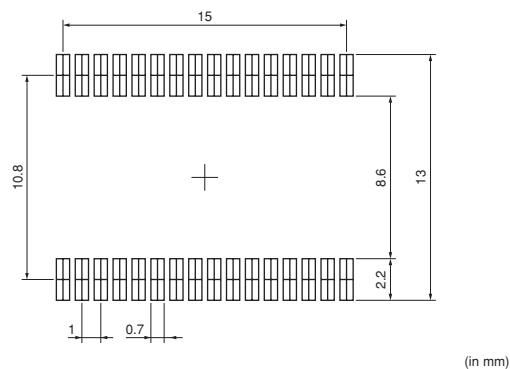
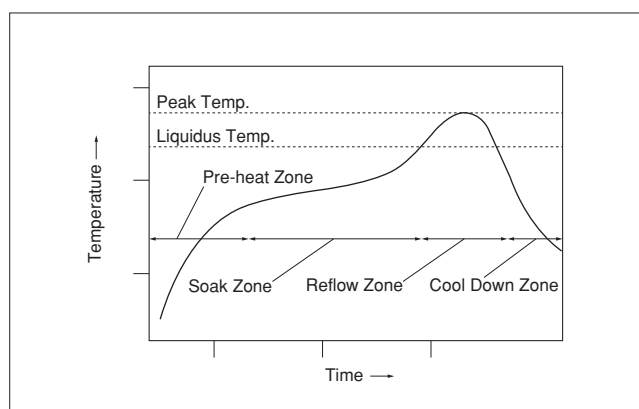


Mounting

■ Land Pattern



■ Reflow Chart



The typical ramp up rate is 3°C/second max. For lead-free soldering with SnAgCu solder the pre-heat temperature zone is ~150-200°C and should last for ~60-180 seconds. Time above the liquidus temperature (~217°C) should be ~60-150 seconds. The reflow peak max. temperature should not exceed 260°C. Temperature within actual peak temperature is typically ~20-40 seconds. Ramp down rate should generally be 6°C/second max.